

CBR06C608B5GAC

General Information

CBR-SMD RF COG, Ceramic, 0.6 pF, +/-0.1 pF, 50 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0603



CBR-SMD RF COG Series Style SMD Chip Description SMD, Fixed, RF, Ultra High Q, Low ESR, Class I Features Ultra High Q, Low ESR, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No Typical Component Weight 5.29 mg Notes Solder Wave or Solder Reflow. Shelf Life 78 Weeks MSL 1

Dimensions	
Chip Size	0603
L	1.6mm +/-0.1mm
W	0.8mm +/-0.1mm
т	0.8mm +/-0.07mm
В	0.4mm +/-0.15mm

Pa	cka	ging Specificat	ions

Packaging Packaging Quantity T&R, 180mm, Plastic Tape 4000

Specifications	
Capacitance	0.6 pF
Tolerance	+/-0.1 pF
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.243%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	412

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